

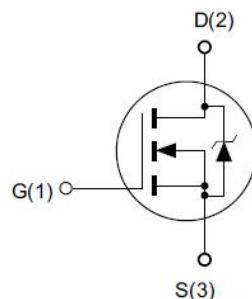


MPF04N65

N-Channel Power MOSFET

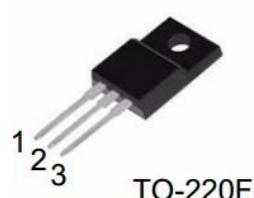
Features

- ◆ 650V, 4A, $R_{DS(ON)}$ (Typ.) = 2.3Ω@VGS = 10V.
- ◆ Low Crss
- ◆ Fast Switching
- ◆ 100% Avalanche Tested



Application

- ◆ Charger
- ◆ Standby Power



Absolute Maximum Ratings $T_c = 25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | Limit | Unit |
|----------------|--|------------|------|
| | | TO-220F | |
| V_{DS} | Drain-Source Voltage ^a | 650 | V |
| V_{GS} | Gate-Source Voltage | ± 30 | V |
| I_D | Drain Current-Continuous, $T_c = 25^\circ\text{C}$ | 4 | A |
| | Drain Current-Continuous, $T_c = 100^\circ\text{C}$ | 2.5 | A |
| I_{DM} | Drain Current-Pulsed ^b | 16 | A |
| P_D | Maximum Power Dissipation @ $T_J = 25^\circ\text{C}$ | 33 | W |
| E_{AS} | Single Pulsed Avalanche Energy ^d | 125 | mJ |
| T_J, T_{STG} | Operating and Store Temperature Range | -55 to 150 | °C |

Thermal Characteristics

| Symbol | Parameter | Value | Unit |
|-----------|--|-------|------|
| R_{eJC} | Thermal Resistance, Junction-Case Max. | 3.79 | °C/W |
| R_{eJA} | Thermal Resistance Junction-Ambient Max. | 62.5 | °C/W |

Electrical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted.

Off Characteristics

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Unit |
|------------|-----------------------------------|---|------|------|-----------|------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$ | 650 | - | - | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS} = 650\text{V}, V_{GS} = 0\text{V}$ | - | - | 1 | μA |
| I_{GSS} | Forward Gate Body Leakage Current | $V_{DS} = 0\text{V}, V_{GS} = \pm 30\text{V}$ | - | - | ± 100 | nA |



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■ On Characteristics

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Unit |
|--------------|--|--------------------------------------|------|------|------|----------|
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS} = V_{GS}$, $I_D = 250\mu A$ | 2 | - | 4 | V |
| $R_{DS(on)}$ | Static Drain-Source On-Resistance ^c | $V_{GS} = 10V$, $I_D = 2A$ | - | 2.3 | 2.7 | Ω |

■ Dynamic Characteristics

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Unit |
|-----------|------------------------------|---|------|------|------|------|
| C_{iss} | Input Capacitance | $V_{DS} = 25V$, $V_{GS} = 0V$, $f = 1.0MHz$ | - | 610 | - | pF |
| C_{oss} | Output Capacitance | | - | 53 | - | pF |
| C_{rss} | Reverse Transfer Capacitance | | - | 3.5 | - | pF |

■ On Characteristics

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Unit |
|--------------|---------------------|---|------|------|------|------|
| $t_{d(on)}$ | Turn-On Delay Time | $V_{DD} = 325V$, $I_D = 4A$, $R_G = 25\Omega$, $V_{GS} = 10V$ | - | 12.7 | - | ns |
| t_r | Turn-On Rise Time | | - | 17.4 | - | ns |
| $t_{d(off)}$ | Turn-Off Delay Time | | - | 30.9 | - | ns |
| t_f | Turn-Off Fall Time | | - | 10.5 | - | ns |
| Q_g | Total Gate Charge | $V_{DS} = 520V$, $I_D = 4A$, $V_{GS} = 10V$ | - | 14.2 | - | nC |
| Q_{gs} | Gate-Source Charge | | - | 5.5 | - | nC |
| Q_{gd} | Gate-Drain Charge | | - | 3.8 | - | nC |

■ Drain-Source Diode Characteristics

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Unit |
|----------|---|---------------------------------|------|------|------|------|
| I_s | Drain-Source Diode Forward Continuous Current | $V_{GS} = 0V$ | - | - | 4 | A |
| I_{SM} | Maximum Pulsed Current | $V_{GS} = 0V$ | - | - | 16 | A |
| V_{SD} | Drain-Source Diode Forward Voltage | $V_{GS} = 0V$, $I_s = 4A$ | - | - | 1.4 | V |
| T_{rr} | Body Diode Reverse Recovery Time | $di/dt = 100A/us$ $I_F = 4A$ | - | 264 | - | ns |

Notes:

- a. $T_J = +25^\circ C$ to $+150^\circ C$.
- b. Repetitive rating; pulse width limited by maximum junction temperature.
- c. Pulse width $\leq 300\mu s$; duty cycle $\leq 2\%$.
- d. $L = 10mH$, $V_{DD} = 50V$, $I_{as} = 5A$, $R_G = 25\Omega$ Starting $T_J = 25^\circ C$.

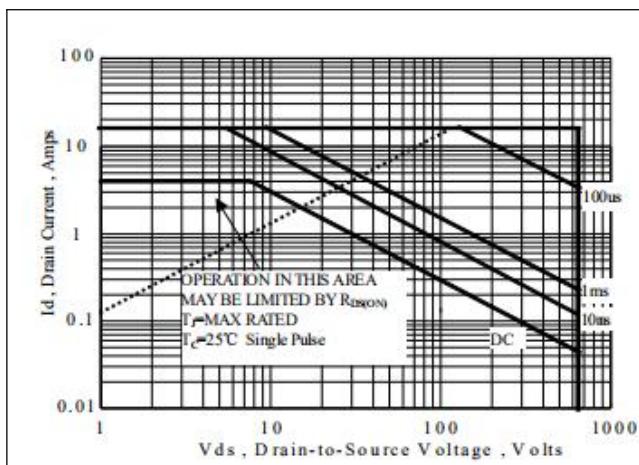


Figure 1. Maximum Safe Operating Area

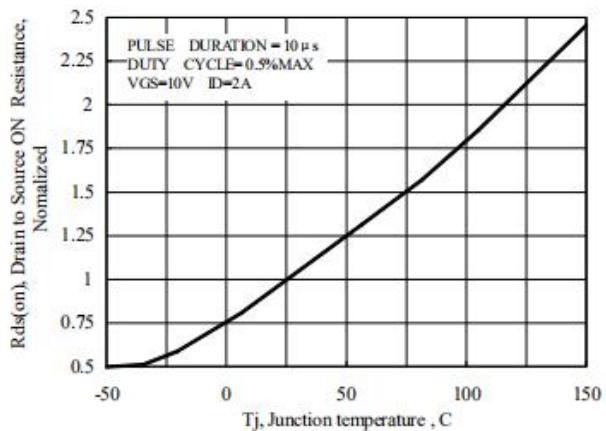


Figure 2. Normalized On-Resistance Variation with Temperature

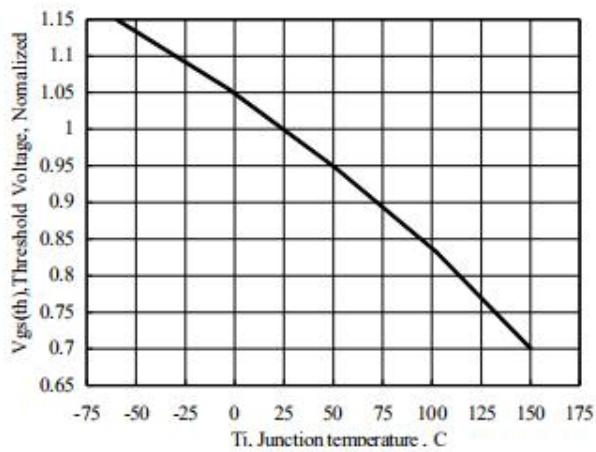


Figure 3. Typical Threshold Voltage vs Junction Temperature

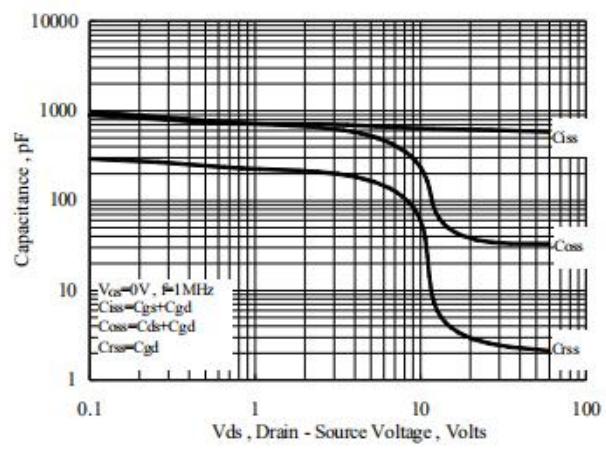


Figure 4. Capacitance Characteristics

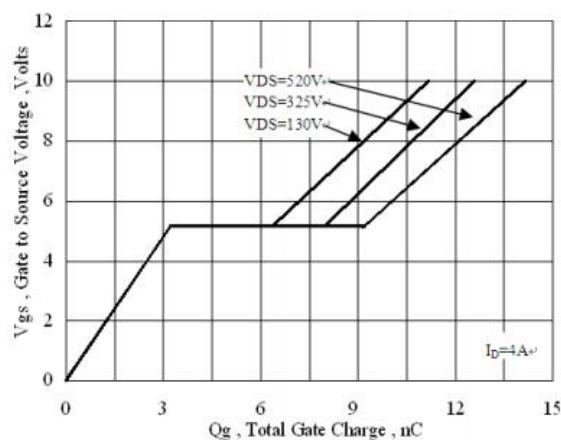


Figure 5. Gate Charge Characteristics

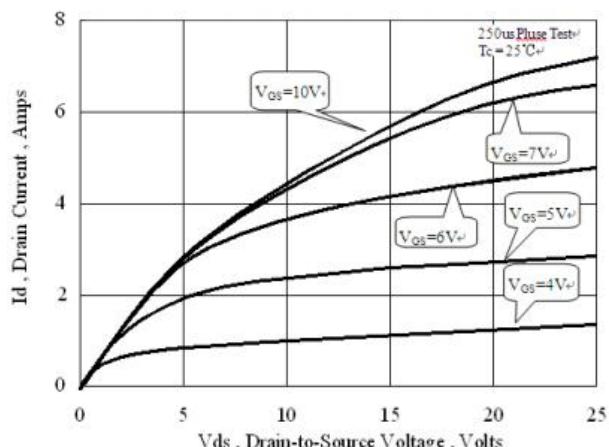


Figure 6. On-State Characteristics

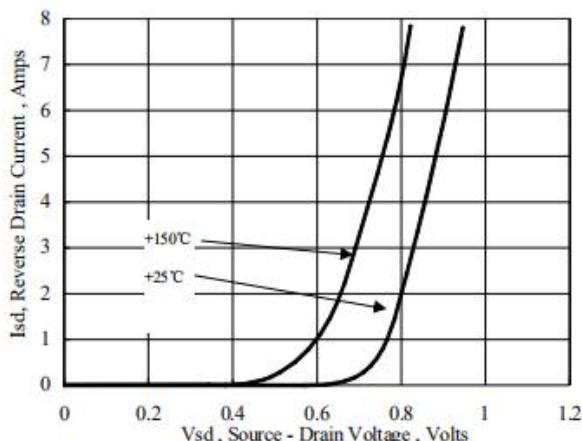


Figure 7. Typical Body Diode Transfer Characteristics

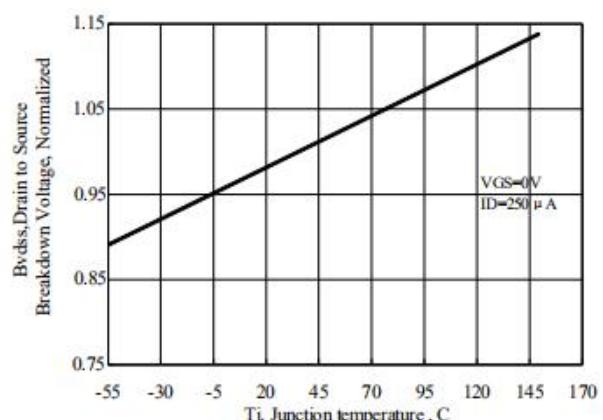


Figure 8. Typical Breakdown Voltage vs Junction Temperature

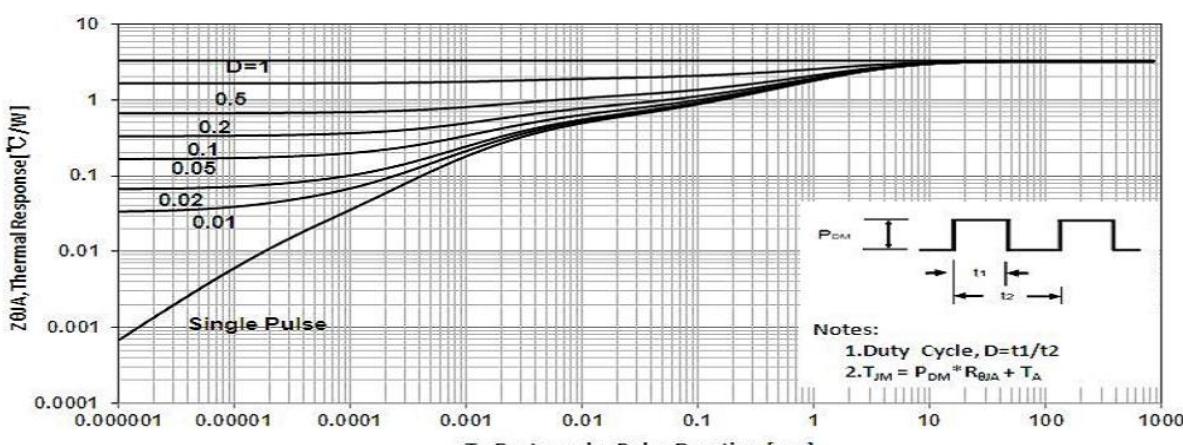


Figure 9. Normalized Effective Transient Thermal Impedance With Pulse Duration

■ Package Information

